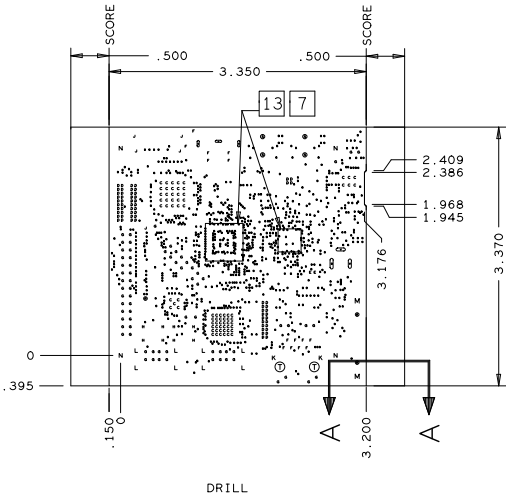
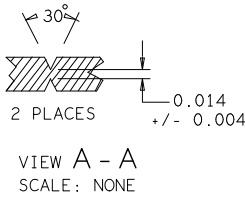


DRILL CHART: TOP to BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
•	8.0	+0.0/-8.0	PLATED	1030
•	12.0	+0.0/-12.0	PLATED	72
•	28.0	+3.0/-3.0	PLATED	64
•	30.0	+3.0/-3.0	PLATED	2
•	38.0	+3.0/-3.0	PLATED	14
•	40.0	+3.0/-3.0	PLATED	71
•	43.0	+3.0/-3.0	PLATED	8
•	51.0	+3.0/-3.0	PLATED	5
•	70.0	+3.0/-3.0	PLATED	2
•	90.0	+3.0/-3.0	PLATED	8
•	120.0	+3.0/-3.0	PLATED	2
•	156.0	+3.0/-3.0	PLATED	4
•	35.0	+3.0/-3.0	NON-PLATED	1
•	60.0	+3.0/-3.0	NON-PLATED	2
•	63.0	+3.0/-3.0	NON-PLATED	4
•	128.0	+3.0/-3.0	NON-PLATED	2
•	86.0x28.0	+3.0/-3.0	PLATED	2
•	86.0x28.0	+3.0/-3.0	PLATED	1
•	120.0x40.0	+3.0/-3.0	PLATED	1
•	120.0x40.0	+3.0/-3.0	PLATED	1
•	140.0x40.0	+3.0/-3.0	PLATED	1



NOTES: UNLESS OTHERWISE SPECIFIED

- TOTAL BOARD THICKNESS SHALL BE .062 +/- .007 INCHES.
ALL MATERIAL SHALL BE 370HR MATERIAL USING A LEAD FREE PROCESS.
- THIS DRAWING SPECIFIES THE REQUIREMENT FOR A MULTILAYER PRINTED BOARD IN ACCORDANCE WITH SPECIFICATION IPC-6012 CLASS 2. THE FOLLOWING PARAMETERS APPLY:
 - MEETS RoHS DIRECTIVE WITH 94V-0 FLAMMABILITY RATING
 - IS LEAD FREE PROCESS COMPATIBLE WITH A MIN. OF 5 CYCLES AT 260degC FOR 10 SECONDS.
 - MIN. Tg AND Td OF 180 degC AND 330 degC, RESPECTAVILY.
- COPPER PLATED SURFACE CONDUCTORS SHALL BE THE EQUIVALENT OF 1 OZ. COPPER AFTER PLATING. PLANE LAYERS SHALL BE 1 OZ. COPPER. AVERAGE COPPER ON THE WALL OF THE PLATED HOLE SHALL BE .001 INCH.
- MINIMUM TRACE AND SPACE SHALL BE .003 OF AN INCH.
- SOLDERMASK ON BOTH SIDES OF THE BOARD SHALL BE S.M.O.B.C., LDI, COLOR RED. SOLDERMASK SHALL NOT BE MODIFIED.
- PLATED THRU HOLE SIZE TOLERANCES SHALL BE +/- .003 INCH.
UNPLATED THRU HOLE SIZE TOLERANCES SHALL BE +/- .002 INCH.
- VIAS SHALL BE FILLED WITH NON-CONDUCTIVE EPOXY, PLATED AND PLANERIZED.
- SILKSCREEN ON BOTH SIDES OF THE BOARD SHALL BE WHITE EPOXY INK. NO SILK ON PADS. PWB LEAD FREE AND RoHS MARKINGS:
 - PWB SHALL BE MARKED LEAD FREE WITH AN INK STAMP Pb
 - PWB SHALL BE MARKED LEAD FREE PROCESS COMPATIBLE WITH AN INK STAMP $\text{260}^{\circ}\text{C}$
 - OTHER MANUFACTURING MARKINGS MAY USE TOP/BOTTOM SIDE ETCH.
- DRC'S MUST BE RUN ON THE GERBERS BEFORE BUILDING BOARDS UNLESS PRIOR APPROVAL IS GIVEN IN WRITING.
- FINISHED BOARD SHALL BE FREE OF BURRS ON EDGES.
- SURFACE FINISH SHALL BE IMMERSION SILVER.
- IMPEDENCE CONTROLLED, +/- 10%.
90 OHM DIFF. - 4.1 MIL LINE / 7.9 MIL SPACING.
100 OHM DIFF. - 3.4 MIL LINE / 10.6 MIL SPACING
- REGISTRATION OF SOLDERMASK SHALL BE +/- .002.



TSLK
SMC
LAYER 1
LAYER 2
LAYER 3
LAYER 4
LAYER 5
LAYER 6
SMS
BSLK

LAYER SCHEDULE
SCALE: NONE

		APPROVED			TEXAS INSTRUMENTS	
		CHECKED				
		DRAFTING	CalCad, Inc.		FABRICATION DRAWING, BEAGLE XM, REV. C1	
DATE 08/16/11		ENGR				
DESIGN ENGR		TOLERANCES UNLESS OTHERWISE SPECIFIED X.XX ± 0.01 X.XXX ± 0.005 ANGLES ± 1/8°				
PROJECT ENGR						
ENGR MGR						
NEXT ASSEMBLY		DO NOT SCALE DRAWING		SCALE NONE	SHEET 1 OF 2	SIZE D